

Abstract

CHUCKING MECHANISM, ARTICLE MANUFACTURING APPARATUS, SEMICONDUCTOR MANUFACTURING APPARATUS

A chucking mechanism includes a tool (21) configured to chuck a workpiece (11) by suction, a tool holder (22) including a suction path (116), and a positioning portion (117) that positions a relative position of the tool (21) with respect to the tool holder (22) in a case where the tool holder (22) holds the tool (21), in which the positioning portion (117) includes at least one convex portion (102) arranged on one of the tool (21) and the tool holder (22), the at least one convex portion (102) being formed from an elastic material and including a tapered surface (107), and at least one concave portion (112) arranged on the other of the tool (21) and the tool holder (22) and configured to fit the convex portion (102).

[Figure 3]